



S/N 10/747927

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Paul A. Koning et al.	Examiner:	Unknown
Serial No.:	10/747927	Group Art Unit:	Unknown
Filed:	December 30, 2003	Docket:	884.863US1
Title:	NANOTUBE MODIFIED SOLDER THERMAL INTERMEDIATE STRUCTURE, SYSTEMS, AND METHODS		
Assignee:	Intel Corporation	Customer No:	21186

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No : 10/747927

Filing Date: December 30, 2003

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Assignee: Intel Corporation

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Dkt: 884.863US1 (INTEL)

The present application is either a U.S. national patent application filed after June 30, 2003 or an international application that entered the national stage under 35 U.S.C. § 371 after June 30, 2003. Thus, Applicant believes that the U.S. Patent & Trademark Office has waived the requirement under 37 C.F.R. 1.98 (a)(2)(i) for submitting a copy of each cited U.S. patent and each U.S. patent application publication. The waiver is provided in a pre-OG notice from the U.S. Patent & Trademark Office entitled "Information Disclosure Statements May Be Filed Without Copies of U.S. Patents and Published Applications in Patent Applications filed after June 30, 2003" and dated July 11, 2003. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

PAUL A. KONING ET AL.

By their Representatives,

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Date

April 28, 2004

By

Charles E. Steffey  
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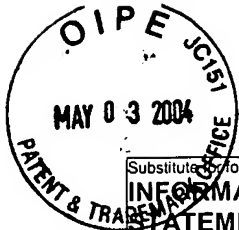
CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 28 day of April, 2004.

Name

KACIA LEE

Signature

Kacia Lee



Substitute Form 1449A/PTO

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Complete if Known

Application Number	10/747927
Filing Date	December 30, 2003
First Named Inventor	Koning, Paul
Group Art Unit	Unknown
Examiner Name	Unknown

Sheet 1 of 1

Attorney Docket No: 884.863US1

**US PATENT DOCUMENTS**

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-2003/0117770	06/26/2003	Montgomery, Stephen W.	361	687	12/20/2001
	US-5,316,080	05/31/1994	Banks, Bruce A., et al.	165	185	02/10/1993
	US-5,604,037	02/18/1997	Ting, Jyh-Ming, et al.	428	408	11/01/1994
	US-5,825,624	10/20/1998	Arnold, Judson V., et al.	361	708	02/05/1997
	US-5,837,081	11/17/1998	Ting, Jyh-Ming, et al.	156	89.26	03/13/1996
	US-5,965,267	10/12/1999	Nolan, Peter E., et al.	428	408	03/31/1998
	US-6,312,303	11/06/2001	Yaniv, Zvi, et al.	445	24	07/19/1999
	US-6,630,772	10/07/2003	Bower, Christopher A., et al.	313	311	04/22/1999

**FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T <sup>2</sup>
	EP-0538798	04/28/1993	Iguchi, T., et al.	H01L	23/373	
	EP-0689244	12/27/1995	Anthony, T. R.	H01L	23/373	

**OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
		BELLAR, R J., et al., "High Conduction Thermal Interface Material", <u>IBM Technical Disclosure Bulletin</u> , 36 (10), (October 1, 1993), 581-583	

EXAMINER

DATE CONSIDERED

Substitute Disclosure Statement Form (PTO-1449)

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. <sup>1</sup> Applicant's unique citation designation number (optional) <sup>2</sup> Applicant is to place a check mark here if English language Translation is attached